

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of  
Invention

MASK AND SUBSTRATE ALIGNMENT FOR SOLDER  
BUMP PROCESS

Application Number:

Confirmation Number:

First Named Applicant: Duane Allen

Attorney Docket Number: BUR920030027US1

Search string: ( 6327034 or 6274198 or 6030889 or 5324012 or 5296916 or 4915057 or  
4755053 or 4746548 or 4544311 or 3647533 or 20010030747 ).pn.

## US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6327034	2001-12-04	Hoover et al			
	2	6274198	2001-08-14	Dautartas			
	3	6030889	2000-02-29	Aulicino et al			
	4	5324012	1994-06-28	Aoyama et al			
	5	5296916	1994-03-22	Kelly et al			
	6	4915057	1990-04-10	Boudreau et al			
	7	4755053	1988-07-05	Levinson et al			
	8	4746548	1988-05-24	Boudreau et al			
	9	4544311	1985-10-01	Husain			
	10	3647533	1972-03-07	Hicks			

## US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20010030747	2001-10-18	Hoover et al			

Signature

Examiner Name

Date

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